



ES Components

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Acronym	Definition
DLA	"Defense Logistics Agency"; controls all Department of Defense' Specifications and Certifications
DSCC	"Defense Supply Center Columbus". Name changed to DLA (above)
JEDEC	Joint Electronic Device Engineering Council develops open standards for semiconductor devices (1N and 2N PN's are typically JEDEC standard devices)
MIL-STD-750	DLA " How to perform Methods " for Discretes (Diodes, JFETs, Mosfets, Transistors)
MIL-STD-883	DLA " How to perform Methods " for IC's, passives and all components not covered by -750 above
MIL-PRF-19500	DLA " What to test/performance " spec for Packaged and Die DISCRETs (Diodes, JFETs, Mosfets, Transistors). It also outlines its own Element Evaluation (LAT) for die.
MIL-PRF-38534	DLA " What to test/performance " spec for Packaged HYBRIDS and MCM's (Multi-Chip Modules). It also outlines its own Element Evaluation (LAT) for die.
MIL-PRF-38535	DLA " What to test/performance " spec for INTEGRATED CIRCUITS (IC's). Generally a single chip in a package however there are multi-chip exceptions.
MIL-M-38510	Obsolete Specification but still found on some customer drawings. MIL-M38510 have been superseded by MIL-PRF-38535 and 38534.
QML	DLA Controlled "Qualified Manufacturers List".
QPL	DLA controlled "Qualified Product List". Only QMLs can make QPLs.
/sheet	Slash-sheet. Refers to 19500/XYZ drawings. Initiated and controlled by DLA part number drawings for specific parts. Listed on QPL by manufacturer.
SCD	Source Control Drawing (controlled by Customer, not DLA)
SMD	Standard Military Drawing initiated by Manufacturers and controlled by DLA. Part numbers begin with: 5962-
QCI	"Quality Conformance Inspection", included in 19500, 38534 and 38535. Groups A, B, C, D, E defines further testing of samples after 100% screening is complete, for further qualifications (example: Life test burn-in).
RoHS	RoHS: (pronounced Row-hass), denotes no lead (Pb) in the plating; "lead free" Part numbers typically have a suffix -E3 or M3 to indicate RoHS plating RoHS plating is not allowed for the majority of Mil/Aero applications
Device Prefixes for Military/Space Grade Semiconductors	
Packaged devices, 19500 Discretes (including Siliconix JAN JFETs and Mosfets):	
JAN	Joint Army Navy; "JAN" as a prefix by itself is obsolete
JANTX	JANTX: TX = Testing extra = 100% screening, including environmental & burn-in.
JANTXV	JANTXV: same as TX, plus 100% die Visual inspection before sealing the package (pre-cap visual). JANTXV can be used to support JANTX requirements, not the other way around
JANS	"Space" grade, TXV + extended screening, longer burn-in, SEM, PIND, etc. JANS wafer fab requirements are more rigorous than JANTXV wafer fab.
DIE devices per 19500 Discrete families (Diodes, JFET's, Mosfets, Transistors):	
JANHC	Die equivalent for JANTXV semiconductors; "Military" grade die
JANKC	Die equivalent for JANS Semiconductors: "Space" grade die
JANKCR	Space grade die with Radiation Performance guaranteed to 100Krad
JANCF	Space grade die with Radiation Performance guaranteed to 300Krad
Packaged devices, IC's per 38535, (Siliconix Analog Switches)	
5962-xxxxx	5962-xxxxx: 5962 is prefix for Military Grade IC packaged devices per SMD's
Suffix /883	Indicates QML device requirements with screening/QCI, example:: DG201/883B. Suffix for "Compliant" MIL-PRF-38535 Packaged Devices.
Note: There are no JANHC or JANKC Die products for Integrated Circuits, "equivalent" only.	